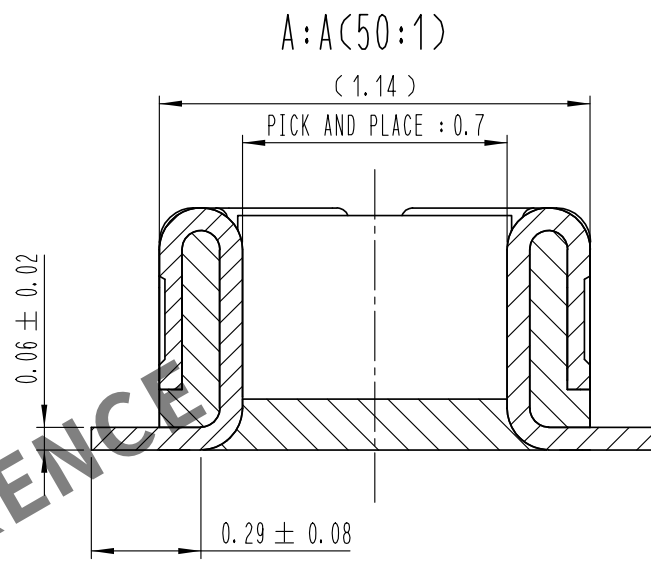
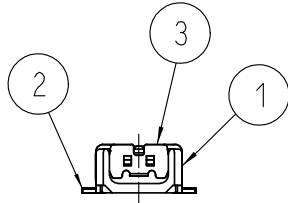
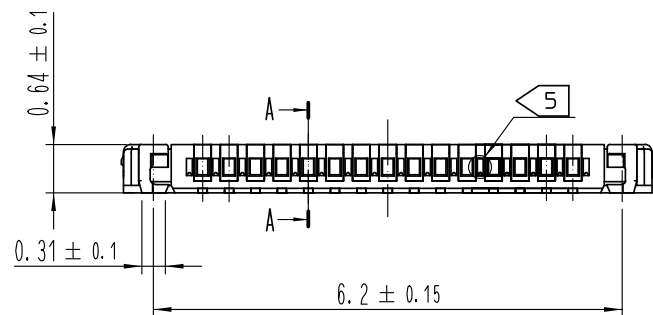
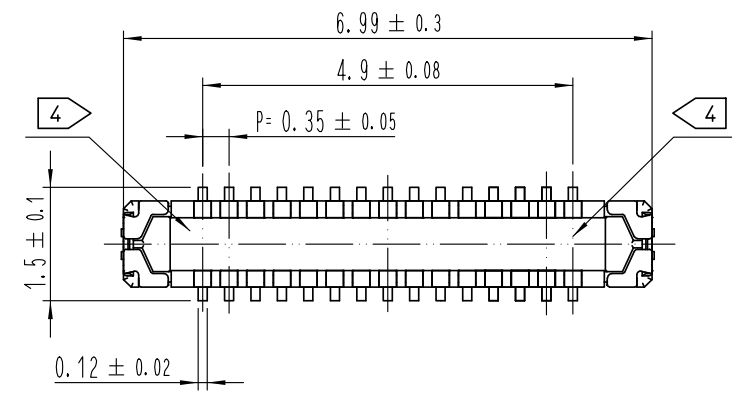


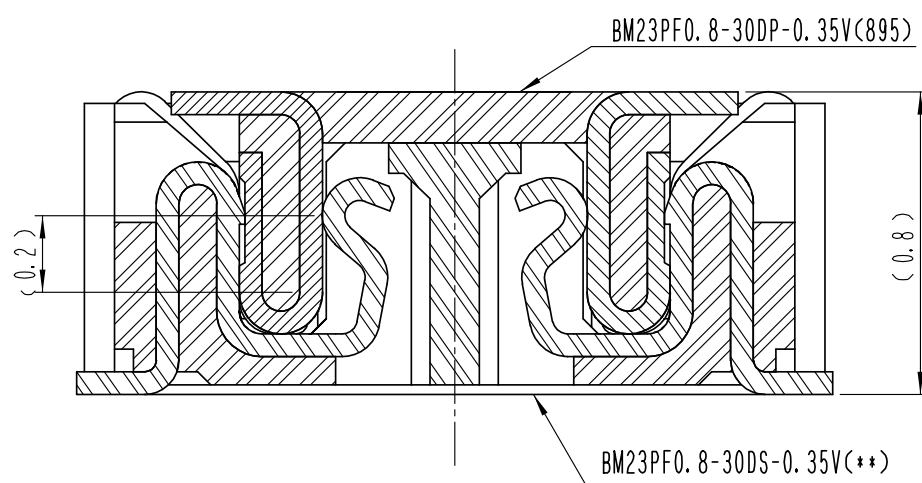
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△數 COUNT		訂正事項 DESCRIPTION OF REVISIONS	擔當 B	檢圖 Y	年月日 DATE	△數 COUNT		訂正事項 DESCRIPTION OF REVISIONS	擔當 B	檢圖 Y	年月日 DATE
△						△					
△						△					
△						△					



ENGAGEMENT FIGURE (50:1)



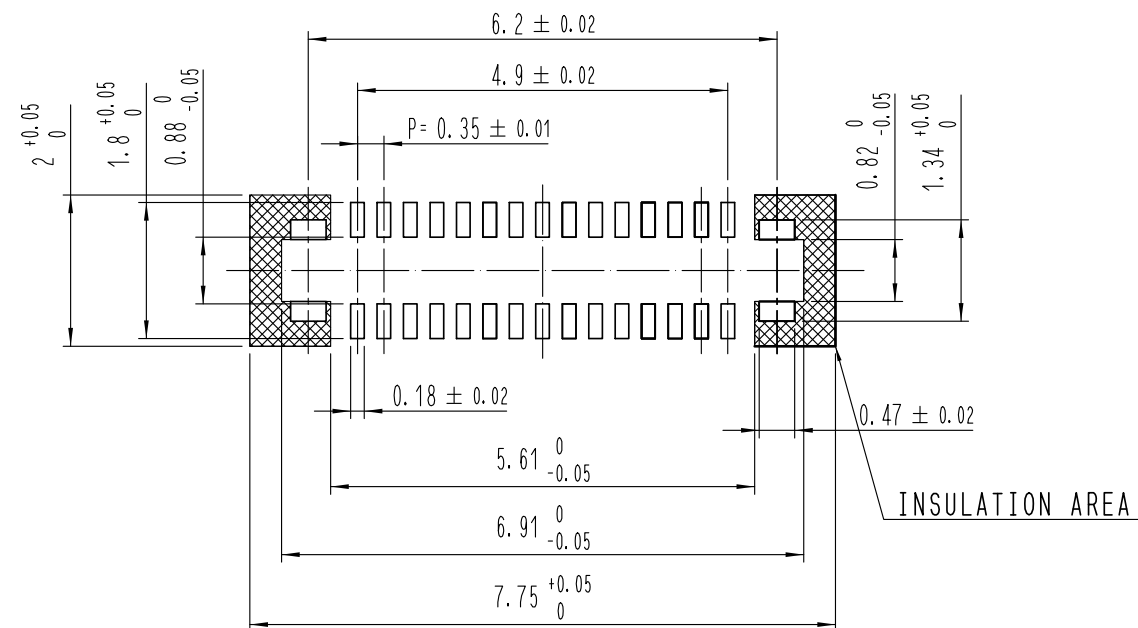
- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
 - 2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μm MIN.
SMT LEAD : GOLD 0.05 μm MIN.
UNDER PLATING : NICKEL 1 μm MIN.
(SURFACE : SEALING)
 - 3. METAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μm MIN.
UNDERPLATING : NICKEL 1 μm MIN.
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
 - 5. A PART OF THE WALL COULD BE NOTCHED.

4	PS	CLEAR (EMBOSSED CARRIER TAPE)			
3	COOPER ALLOY	3			
2	COOPER ALLOY	2	6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
REMARKS			DRAWN	DESIGNED	CHECKED
			Y. J. LEE 17. 08. 09	Y. J. LEE 17. 08. 09	H. W. JO 17. 08. 09
			APPROVED	RELEASED	
			T. S. KANG 17. 08. 09	17. 08. 09	
CODE NO. (OLD)	SCALE	DRAWING NO.	PART NO.		
	10:1	EDC3-631975	BM23PF0.8-30DP-0.35V(895)		
	UNITS	HRS HIROSE KOREA CO., LTD.	CODE NO		
	mm		CL 6644-0055-6-895		
					1/3

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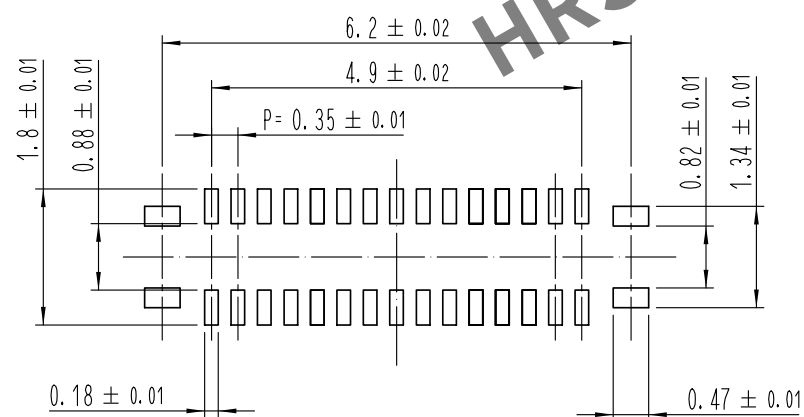
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7 RECOMMENDED PCB LAYOUT

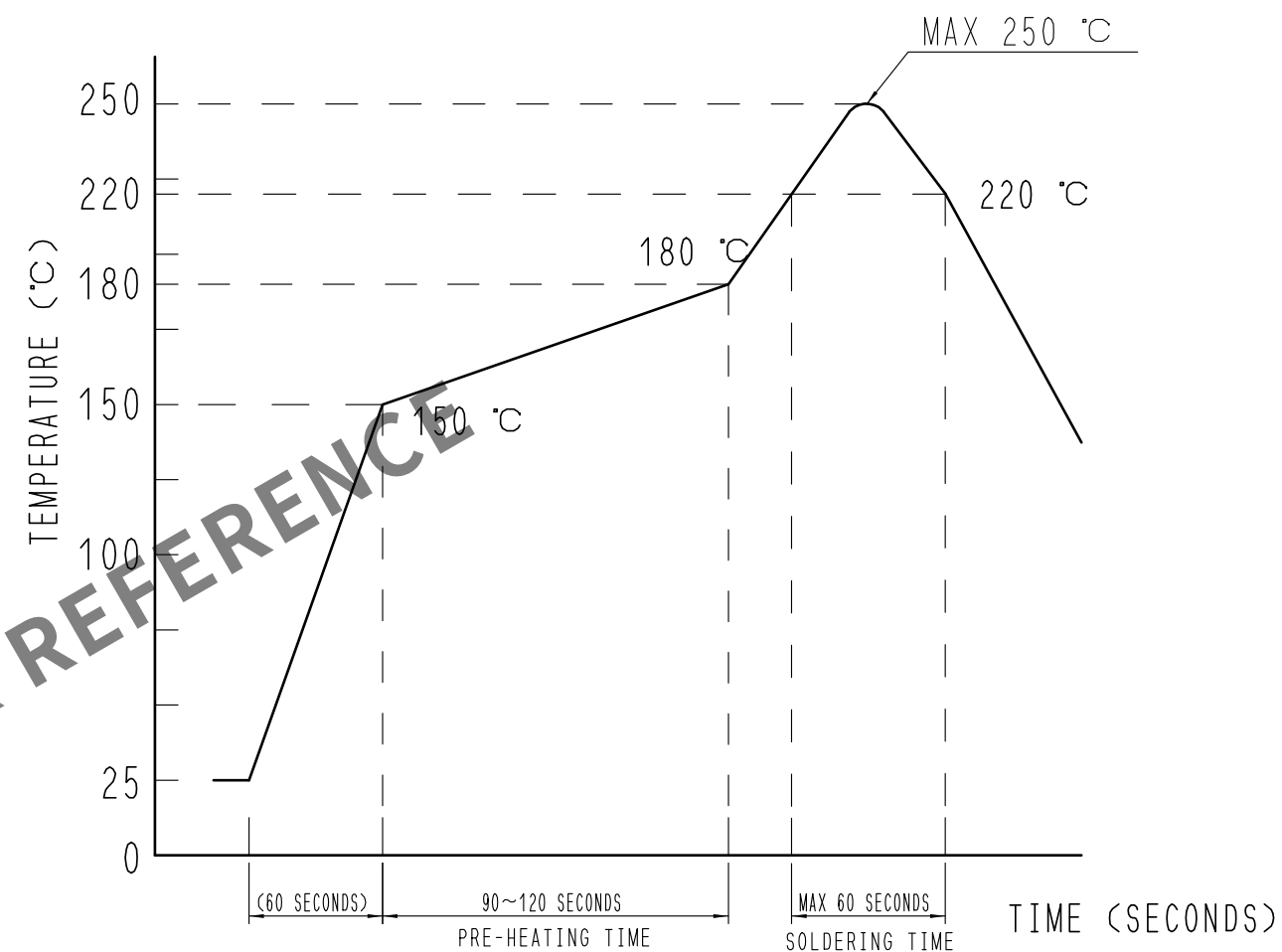


RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : $100 \mu\text{m}$



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N_2 REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220 $^{\circ}\text{C}$: 60 SEC MAX.
(PEAK TEMPERATURE: 250 $^{\circ}\text{C}$ MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE(MIN): 150 $^{\circ}\text{C}$
PRE-HEAT TEMPERATURE(MAX): 180 $^{\circ}\text{C}$
PRE-HEAT TIME: 90-120 SEC.

- 6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-631975	PART NO.	BM23PF0.8-30DP-0.35V(895)
SCALE	10:1	HRS HIROSE KOREA CO., LTD.	CODE NO.	CL 6644-0055-6-895
UNITS	mm			

